

XKB Connectivity

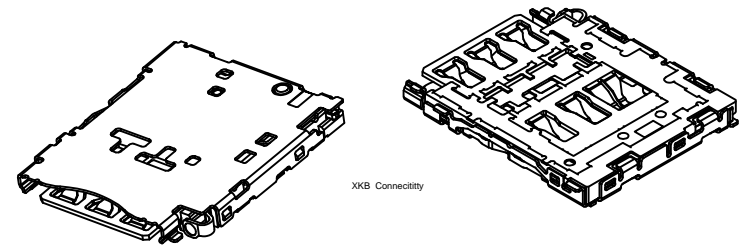
NOTE:

- 材料 Material:
 - 1-1 胶壳 Housing: High Temperature Thermoplastic(LCP S475)Color Black UL 94V-0
 - 1-2 触点 Contact: Phosphor Bronze(C5210R-H,T=0.08±0.01mm)
 - 1-3 外壳 Cover: SUS301-HT=0.15±0.03mm
- 电镀 Plating:
 - 2-1 接触端子 Contact terminal:
 - 接触电阻 Contact area: Gold 1u" Min.
 - 焊接区 Solder area: Gold 0.8u"Min
 - 底镀 Underplating: Ni overall 50U"Min.
 - 2-2 外壳 Cover:
 - 底镀 Underplating: Ni overall 30U"Min.
 - 焊接区 Solder area: Gold 0.8u"Min.
- 规格 Specification:
 - 3-1. 额定电流 Current Rating :0.5A max.
 - 3-2. 接触电阻 Contact Resistance:50 mohms max
 - 3-3. 绝缘电阻 Insulation Resistance:1000 Mohms min./500VDC
 - 3-4. 耐电压 Dielectric Withstanding Voltage:500 V AC/1minute
 - 3-5. 工作温度 Operating Temperature:-25℃ to+85℃
 - 3-6. 插拔次数 Mating Cycles:5000 Insertions
- Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC
- Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

XKB Connectivity

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



DSND		DATE		SCALE: N/A	MODEL TYPE: SIM CARD CONN
DWN		DATE		VIEW:	PART NO.:
CHKD		DATE		UNIT: mm/in	DWG NO.:
APPD		DATE		SIZE: A4	XKNANO-1131-18
				XKB INDUSTRIAL PRECISION CO., LIMITED	WEIGHT 1.0g
					SHEET 1/1
					REVISION A0

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
					ANGLAR ±5°
ΔX					L ≤ 4 ±0.2
ΔX					4 < L ≤ 16 ±0.3
ΔX					16 < L ≤ 63 ±0.4
					L > 63 ±0.5
REVISIONS					
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn					